

## Application Data Sheet

### Application Information

**Application Type::** Regular  
**Subject Matter::** Utility  
**Suggested classification::**  
**Suggested Group Art Unit::**  
**CD-ROM or CD-R?::** None  
**Computer Readable Form (CRF)?::** No  
**Title::** SEMICONDUCTOR DEVICE, WIRING  
BOARD AND METHOD OF MAKING SAME  
**Attorney Docket Number::** 035532-0135  
**Request for Early Publication?::** No  
**Request for Non-Publication?::** No  
**Suggested Drawing Figure::**  
**Total Drawing Sheets::** 16  
**Small Entity?::** No  
**Petition included?::** No  
**Secrecy Order in Parent Appl.?::** No

### Applicant Information

**Applicant Authority Type::** Inventor  
**Primary Citizenship Country::** Japan  
**Status::** Full Capacity  
**Given Name::** Akira  
**Family Name::** CHINDA  
**City of Residence::** Tokyo  
**Country of Residence::** Japan

**Street of mailing address::** c/o HITACHI CABLE, LTD.  
6-1, Otemachi 1-chome  
Chiyoda-ku, Tokyo  
**Country of mailing address::** Japan

#### **Correspondence Information**

**Correspondence Customer Number::** 22428  
**E-Mail address::** PTOMailWashington@FoleyLaw.com

#### **Representative Information**

<b>Representative Customer Number::</b>	22428	

#### **Domestic Priority Information**

<b>Application::</b>	<b>Continuity Type::</b>	<b>Parent Application::</b>	<b>Parent Filing Date::</b>

#### **Foreign Priority Information**

<b>Country::</b>	<b>Application number::</b>	<b>Filing Date::</b>	<b>Priority Claimed::</b>
Japan	2002-261334	09/06/2002	Yes
Japan	2003-105374	04/09/2003	Yes

#### **Assignee Information**

**Assignee name::** HITACHI CABLE, LTD.